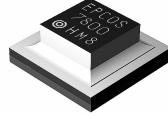




Electronic Parts and Components

SAW Components

Material Data Sheet

Product Family Name	SAW Filters	
	CSSP Package	
Date	31.07.2006	
Version	01	

Construction Element	Material group	Materials	CAS if applicable	mass [weight-%]			Sum [%]	Traces
				min	typical	max		
Active Part							35.5	
	Crystal	LiTaO3	12031-66-2		35.4			
	Metal	Al	7429-90-5		0.1			
Encapsulation							61.7	
	Ceramic	Al2O3	1344-28-1		38.1			
		Cr2O3	1308-38-9		1.9			
		MoO3	1313-27-5		0.1			
		SiO2	14808-60-7		2			
		TiO2	13463-63-7		0.5			
		W	7440-33-7		2.9			
	Metal	Cu	7440-50-8		5.6			
	Polymer	Epoxide / Anhydrite	25928-94-3		4.1			
	Inorganic	Si2O3	14808-60-7		4.1			
	Inorganic	Magnesium Silicate	1343-88-0		1.4			
Polymer	Polyacrylate (PMMA)	9011-14-7		1				
Termination / Conductors							1,6	
	Metal	Ni	7440-02-0		1.5			
	Metal	Au	7440-57-5		0.1			
Internal Connection							1.2	
	Metal	Pb **)	7439-92-1	0.3	0.4	0.5		
	Metal	Sn	7440-31-5	0.7	0.8	0.9		
						total:	100	

Package code:	sizes: L x W x H [mm]	Approx. weight [mg]
B39*-B78*-A510 DCS4A	2x2x0.8	10
Range of ordering code (* - wildcard for all products within this range)		

Company:	EPCOS AG	Important remarks:
Contact:	Peter Geschka, Dep. SAW COM PT RQ	
Phone / Fax	+49 89 636 22188 / +49 89 636 27280	
Mail	mailto:peter.geschka@epcos.com	
<p>The component is RoHS-compatible, what means compatible with the requirements of the directives listed below and with the requirements of the provisions which will result from transformation of the directives into national law to the extent such provisions reflect the Regulations.</p>		<p>1) Traces are product parts, substances etc. that are below a percent tage of 0.1 % by weight, if not otherwise regulated (see note no. 2).</p> <p>2) A list of the (legal) "... restrictions on substances ..." or materials is available at internet address of the EICTA organisation (C4E List)</p> <p>3) All statements herein are based on our present knowledge. If our products are used properly, there are no risks to human beings and/or the environment.</p>



Electronic Parts and Components

Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive 2002/95/EC");
Commission Decision of 18 August 2005 amending Directive 2002/95/EC (2005/618/EC);
Commission Decision of 13 October 2005, of 21 October 2005, of 21 February 2006 amending the Annex to Directive 2002/95/EC (2005/717/EC; 2005/747/EC, 2006/310/EC).

**** exempted by Annex 2002/95/EC (RoHS):**

15 Lead in solders to complete a variable electrical connection between semiconductor die and carrier within integrated circuit Flip Cip packages.

